



Erratum: Effect of Additives on Shape Evolution during Electrodeposition: I. Multiscale Simulation with Dynamically Coupled Kinetic Monte Carlo and Moving-Boundary Finite-Volume Codes [*J. Electrochem. Soc.*, 154, D230 (2007)]

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On page D231, left column, Eq. 2 should appear as

$$\tau = \frac{1}{\sum_j n_j r_j} \quad [2]$$

On page D234, in Table I, column 2, row 15, the first element in the surface reaction should be $\text{Cu(I)HIT}_{\text{ads}}$.

Also on page D234, in Table I, in the last column under section b., the references for both solutions PEG and SPS should be 8, 43.

On page D236, in Table II, the term FEMLAB should be COM-SOL in all three occurrences.

On page D236, left column, line 8 should read calculation was good to the third significant figure.

On page D236, Table III, section b., second column, the value of T should be 298 K.